



60V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C
60V	17mΩ @ V _{GS} = 10V	46.9A
	24mΩ @ V _{GS} = 4.5V	38.3A

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Power Management Functions
- DC-DC Converters
- Backlighting

Features

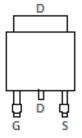
- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- Low R_{DS(ON)} Ensures On State Losses Are Minimized
- Excellent Q_{gd x} R_{DS(ON)} Product (FOM)
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (<u>DMTH6016LK3Q</u>)

Mechanical Data

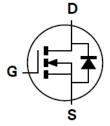
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Weight: 0.33 grams (Approximate)



Top View



Pin Out Top View



Equivalent Circuit

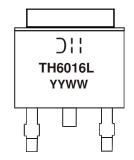
Ordering Information (Note 4)

Part Number	Case	Packaging
DMTH6016LK3-13	TO252 (DPAK)	2,500/Tape & Reel

Notes: 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



Dil =Manufacturer's Marking
TH6016L = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 18 = 2018)
WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	60	V	
Gate-Source Voltage		V_{GSS}	±20	V
Continuous Drain Current (Note 5) V _{GS} = 10V	$T_A = +25^{\circ}C$ $T_A = +100^{\circ}C$	I _D	10.8 7.6	А
Continuous Drain Current (Note 6) $V_{GS} = 10V$ $T_C = +25^{\circ}C$ $T_C = +100^{\circ}C$		I _D	46.9 33.2	Α
Maximum Continuous Body Diode Forward Current (Note 6)	Is	50	Α	
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%)	I _{DM}	70	Α	
Avalanche Current, L=0.1mH	I _{AS}	15.3	Α	
Avalanche Energy, L=0.1mH	E _{AS}	11.7	mJ	

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	3.2	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	47	°C/W
Total Power Dissipation (Note 6)	P_{D}	60	W
Thermal Resistance, Junction to Case (Note 6)	$R_{ heta JC}$	2.5	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	60	-	-	V	$V_{GS} = 0V, I_D = 1mA$	
Zero Gate Voltage Drain Current	I _{DSS}	-	-	1	μΑ	$V_{DS} = 48V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	1	-	3	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance		-	11	17	mΩ	$V_{GS} = 10V, I_D = 10A$	
Static Drain-Source On-nesistance	R _{DS(ON)}	-	16	24	mΩ	$V_{GS} = 4.5V, I_D = 6A$	
Diode Forward Voltage	V _{SD}	-	0.9	1.2	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	-	864	-		$V_{DS} = 30V$, $V_{GS} = 0V$, $f = 1MHz$	
Output Capacitance	Coss	-	282	-	pF		
Reverse Transfer Capacitance	C _{rss}	-	27.1	-			
Gate Resistance	R_g	-	1.35	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 10V)	Qg	-	17	-			
Total Gate Charge (V _{GS} = 4.5V)	Qg	-	8.4	-	nC	V _{DS} = 30V. I _D = 10A	
Gate-Source Charge	Q_{gs}	-	3.1	-	IIC	VDS = 30V, ID = 10A	
Gate-Drain Charge	Q_{gd}	-	4.3	-			
Turn-On Delay Time	t _{D(ON)}	-	3.4	-		$V_{DD} = 30V, V_{GS} = 10V,$ $R_G = 6\Omega, I_D = 10A$	
Turn-On Rise Time	t _R	-	5.2	-	20		
Turn-Off Delay Time	t _{D(OFF)}	-	12.9	-	ns		
Turn-Off Fall Time	t _F	-	6.8	-			
Body Diode Reverse Recovery Time	t _{RR}	-	22	-	ns	1 404 41/-14 4004/	
Body Diode Reverse Recovery Charge	Q _{RR}	-	11.1	-	nC	$I_F = 10A$, di/dt = 400A/ μ s	

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout.6. Device mounted on infinite heat sink and measured by thermal couple attached on bottom heat sink of package.
- 7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.



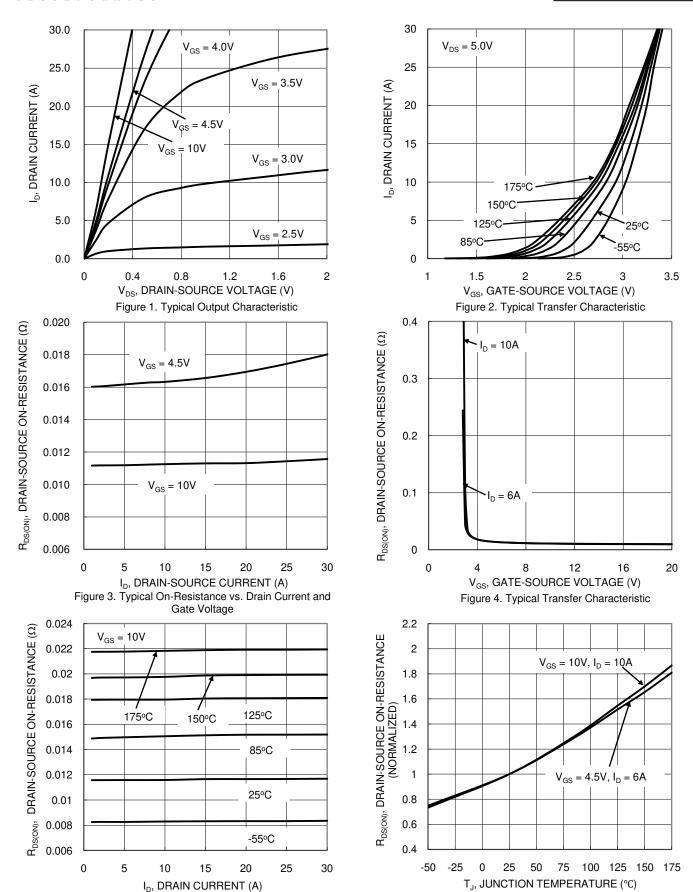


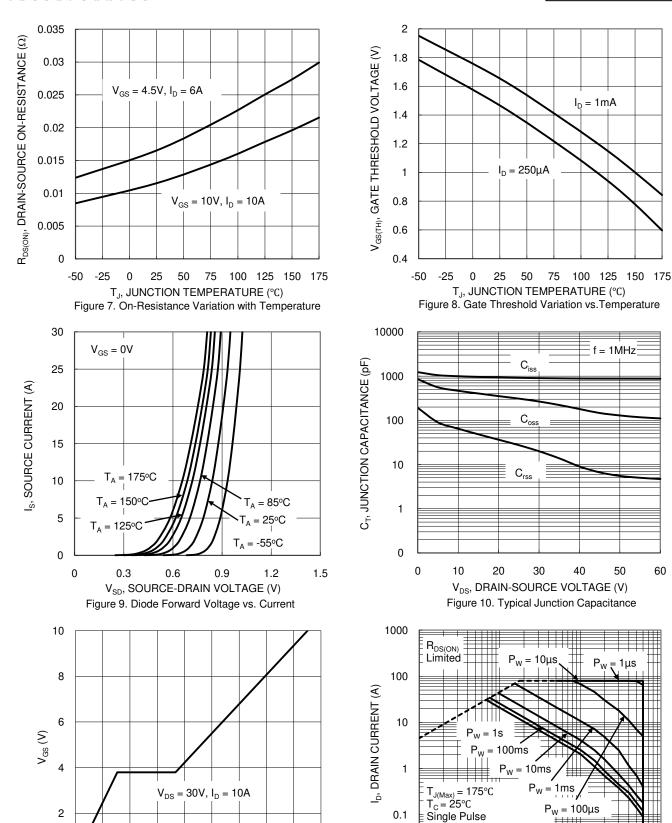
Figure 5. Typical On-Resistance vs. Drain Current and

Temperature

Figure 6. On-Resistance Variation with

Temperature





0

0 2

4

8

10

 Q_{α} (nC)

Figure 11. Gate Charge

12

14

16 18

DUT on Infinite Heatsink

 $V_{GS} = 10V$

0.01

0.1

100

10

V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



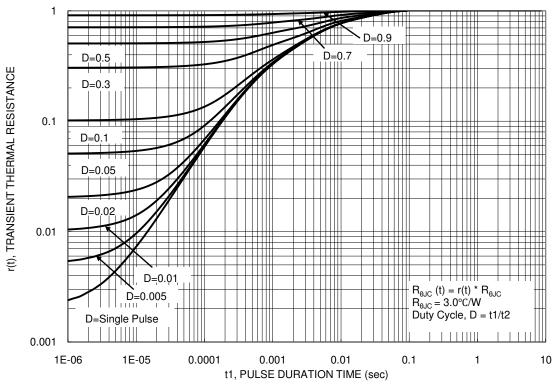
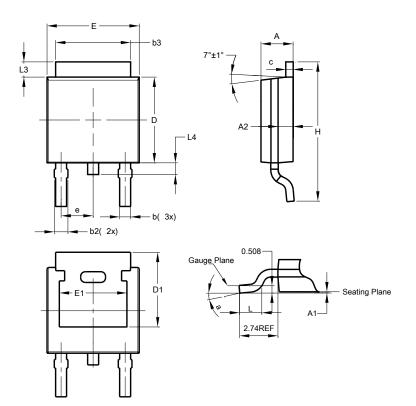


Figure 13. Transient Thermal Resistance



Package Outline Dimensions

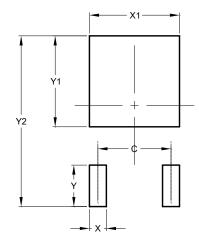
Please see http://www.diodes.com/package-outlines.html for the latest version.



TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A 1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
С	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	-	-		
е	1	-	2.286		
П	6.45	6.70	6.58		
E1	4.32	-	-		
Н	9.40	10.41	9.91		
L	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	-		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)		
C	4.572		
Х	1.060		
X1	5.632		
Υ	2.600		
Y1	5.700		
Y2	10.700		

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